# **Compute Sled**

# HMB-EI00

#### PRELIMINARY



#### **■** Features

- Support 3rd Gen Intel Xeon Scalable Processor (codenamed Ice lake)
- Front Access I/O: Storage bays x2, PCle x1, NIC slot x1, mini-DP port (VGA signal), LOM and USB 3.0 ports
- Support FHHL PCIe by 16 card
- Support OCP NIC 3.0 Modules
- Compatible with HTCA-E400 Series

## **■** Preliminary Specifications

Model	
	HMB-E100A
Processor	
	3rd Gen Intel Xeon Scalable Processor
	(codenamed Ice lake)
Memory	
	DDR4 DIMM x8, LRDIMM+ECC
	Max capacity Dependent on CPU
Front Panel Interface	
	Storage bays x2, PCIe slot x1, NIC slot
	x1, mini-DP port (VGA signal), LOM and
	USB 3.0 ports
System Compatibility	
	HTCA-E400 Series
Temperature	
Operating	0 ~ 40°C
Storage	-40~70°C
Humidity	
	5%~90%. non-condensing
Mechanical	
Dimension (W x H x D)	216.5 x 42.2 x 490.2 mm
Weight	TBD
Certification	
CE	Class A
FCC	Class A

### **■** Ordering Information

HMB-E100A 1U Compute Sled for HTCA-E400

#### ■ Product I/O View





- A Storage bays
  - PCle slot
  - OCP NIC slot
- Mini-DP port(VGA signal)
- E LOM port
- F USB 3.0 port
- Power button

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